

AMENDMENTS

IN THE CLAIMS:

Please amend claim 14, 18, and 20 as provided below.

1-13. (Cancelled).

14. (Currently Amended) A photodiode arrangement, comprising:
a photodiode; and
a submount that is electrically contact-connected to the photodiode,
wherein the photodiode comprises a first metallization on a side facing the
submount, the submount comprises a second metallization on a side facing the
photodiode, the first metallization and the second metallization defining a eutectic
mixture, and the photodiode and the submount are bonded ~~connected~~ to one another
by means of the eutectic mixture ~~bonding~~.

15. (Previously presented) The arrangement as claimed in claim 14, further
comprising one or more alignment marks situated on the photodiode or the submount
or on both the photodiode and the submount.

16. (Previously presented) The arrangement as claimed in claim 14, wherein the
photodiode or the submount or both comprise a silicon chip.

17. (Previously presented) The arrangement as claimed in claim 14, wherein the
photodiode and the submount each have an outer contour that differs from one another
and, accordingly, comprise regions that protrude relative to one another.

18. (Currently Amended) The arrangement as claimed in claim 17, further
comprising contact pads situated on a region of the submount that protrudes with

respect to the photodiode, wherein said contact pads are connected to the second metallization of the submount.

19. (Previously presented) The arrangement as claimed in claim 17, wherein the photodiode comprises an optically active area situated on a region of the photodiode that protrudes with respect to the submount.

20. (Currently Amended) The arrangement as claimed in claim 14, wherein the first metallization of the photodiode comprises a gold metallization and the second metallization of the submount comprises a gold-tin metallization, or vice versa.

21. (Previously presented) The arrangement as claimed in claim 14, wherein one of the photodiode and the submount comprise a trench or cutout on the side facing the other of the photodiode and the submount, thereby ensuring a connection between the photodiode and the submount only in defined regions not associated with the trench.

22-27. (Cancelled).